

Low Power, 24-Bit Sigma-Delta ADC with In-Amp and Embedded Reference (6 Channel)

Preliminary Technical Data

AD7794

FEATURES

Six Differential Analog Inputs
Low Noise Programmable Gain Instrumentation-Amp
RMS noise: 80 nV (Gain = 64)

Bandgap Reference with 5 ppm/C Drift typ

Power

Supply: 2.7 V to 5.25 V operation

Normal: 400 μA typ Power-down: 1 μA max Update Rate: 4 Hz to 500 Hz

Simultaneous 50 Hz/60 Hz Rejection

Internal Clock Oscillator Reference Detect

Programmable Current Sources (10 μA/200 μA/1 mA)

On-Chip Bias Voltage Generator 100 nA Burnout Currents

Low Side Power Switch

Independent Interface Power Supply

24-Lead TSSOP Package

INTERFACE

3-wire serial SPI®, QSPI™, MICROWIRE™, and DSP compatible Schmitt trigger on SCLK

APPLICATIONS

Temperature measurement Pressure measurement Weigh scales

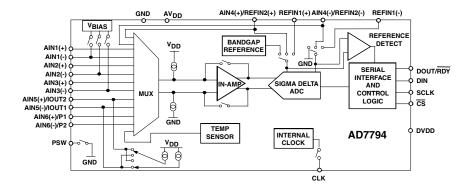
GENERAL DESCRIPTION

The AD7794 is a low power, complete analog front end for low frequency measurement applications. It contains a low noise 24-bit Σ - Δ ADC with six differential inputs. The on-chip low noise instrumentation amplifier means that signals of small amplitude can be interfaced directly to the ADC.

The device contains a precision low noise, low drift internal reference for absolute measurements. An external reference can also be used if ratiometric measurements are required. Other on-chip features include programmable excitation current sources and a bias voltage generator for temperature applications along with 100 nA burnout currents. For pressure and weighscale applications, a low-side power switch is available to power down the bridge between conversions to minimize the power consumption of the system. The device can be operated with the internal clock or, alternatively, an external clock can be used if synchronizing several devices. The output data rate from the part is software programmable and can be varied from 4 Hz to 500 Hz.

The part operates with a power supply from 2.7 V to 5.25 V. It consumes a current of 450 uA maximum and is housed in a 24-lead TSSOP package.

FUNCTIONAL BLOCK DIAGRAM



REV.PrE

6/04.

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REVISION HISTORY

REV.PrE, June 2004: Initial Version

AD7794—SPECIFICATIONS¹

Parameter	AD7794B	Unit	Test Conditions/Comments
AD7794 (CHOP ENABLED)			
Output Update Rate	4	Hz min nom	Settling Time = 2/Output Update Rate
	500	Hz max nom	
No Missing Codes ²	24	Bits min	f _{ADC} ≤125 Hz
Resolution (pk – pk)	16	Bits p-p	Gain = 128, 16.6 Hz Update Rate, V _{REF} = 2.5 V
the boundaries	19	Bits p-p	Gain = 1, 16.6 Hz Update Rate, V _{REF} = 2.5 V
Output Noise and Update Rates	See Tables in ADC Description	5.13 p p	,, roto 12 operate nato, mei 210 r
Integral Nonlinearity	±15	ppm of FSR max	3.5 ppm typ. Gain = 1 to 32
	±25	ppm of FSR max	5 ppm typ, Gain = 64 or 128
Offset Error ³	±3	μV typ	
Offset Error Drift vs. Temperature ⁴	±10	nV/°C typ	
Full-Scale Error ^{3, 5}	±10	μV typ	
Gain Drift vs. Temperature ⁴	±0.5	ppm/°C typ	Gain = 1 or 2
, , , , , , , , , , , , , , , , , , ,	±3	ppm/°C typ	Gain = 4 to 128
Power Supply Rejection	90	dB min	100 dB typ, AIN = FS/2
ANALOG INPUTS	70	up iiiii	100 05 typ// 1111 15/2
Differential Input Voltage Ranges	±REFIN/Gain	V nom	REFIN = REFIN(+) – REFIN(–) or Internal Reference, Gain = 1 to 128
Absolute AIN Voltage Limits ²			
Unbuffered Mode	GND – 30 mV	V min	Gain = 1 or 2
	$AV_{DD} + 30 \text{ mV}$	V max	
Buffered Mode	GND + 100 mV	V min	Gain = 1 or 2
	AV _{DD} – 100 mV	V max	
In-Amp Enabled	GND + 300 mV	V min	Gain = 4 to 128
•	AV _{DD} – 1.1	V max	
Common Mode Voltage	0.5	V min	Gain = 4 to 128
Analog Input Current			
Buffered Mode or In-Amp Enabled			
Average Input Current ²	±200	pA max	
Average Input Current Drift	±2	pA/°C typ	
Unbuffered Mode		pro ctyp	Gain = 1 or 2
Average Input Current	±400	nA/V typ	Input current varies with input voltage.
Average Input Current Drift	±50	pA/V/°C typ	input current varies with input voltage.
Average input current Dint	1	nA max	AIN6(+) / AIN6(-)
Normal Mode Rejection ²	'	IIA IIIax	Allvo(+) / Allvo(-)
Internal Clock			
	70	-ID i	00 -10 + 50 + 1 - 60 + 1 - 56(2.0) 10106
@ 50 Hz, 60 Hz	70	dB min	80 dB typ, 50 ± 1 Hz, 60 ± 1 Hz, FS[3:0] = 1010^6
@ 50 Hz	84	dB min	90 dB typ, 50 ± 1 Hz, FS[3:0] = 1001 ⁶
@ 60 Hz	90	dB min	100 dB typ, 60 ± 1 Hz, $FS[3:0] = 1000^6$
External Clock			
@ 50 Hz, 60 Hz	80	dB min	90 dB typ, 50 ± 1 Hz, 60 ± 1 Hz, FS[3:0] = 1010^6
@ 50 Hz	94	dB min	100 dB typ, 50 ± 1 Hz, $FS[3:0] = 1001^6$
@ 60 Hz	90	dB min	$100 \text{ dB typ}, 60 \pm 1 \text{ Hz}, \text{FS}[3:0] = 1000^6$
Common Mode Rejection			AIN = +FS/2
@DC	90	dB min	FS[3:0] = 1010 ⁶
@ 50 Hz, 60 Hz ²	100	dB min	50 ± 1 Hz, 60 ± 1 Hz, FS[3:0] = 1010 ⁶
@ 50 Hz, 60 Hz ²	100	dB min	50 ± 1 Hz (FS[3:0] = 1001 ⁶), 60 ± 1 Hz (FS[3:0] = 1000 ⁶)

Parameter	AD7794B	Unit	Test Conditions/Comments
REFERENCE INPUT		-	
Internal Reference Initial Accuracy	1.17 ±0.01%	V min/max	
Internal Reference Drift	5	ppm/°C typ	
	15	ppm/°C max	
Internal Reference Noise	2	μV RMS	Gain = 1, Update Rate = 16.6 Hz. Includes ADC Noise.
External REFIN Voltage	2.5	V nom	REFIN = REFIN(+) - REFIN(-)
Reference Voltage Range ²	0.1	V min	
	AV_DD	V max	
Absolute REFIN Voltage Limits ²	GND – 30 mV	V min	
_	$AV_{DD} + 30 \text{ mV}$	V max	
Average Reference Input Current	400	nA/V typ	
Average Reference Input Current Drift	±0.03	nA/V/°C typ	
Normal Mode Rejection ²	Same as for Analog		
	Inputs		
Common Mode Rejection	Same as for Analog		
	Inputs		
Reference Detect Levels	0.3	V min	NOXREF Bit Inactive if VREF < 0.3 V
	0.65	V max	NOXREF Bit Active if VREF > 0.65 V

Parameter	AD7794B	Unit	Test Conditions/Comments
AD7794 (CHOP DISABLED)			
Output Update Rate	4	Hz min nom	Settling Time = 1/Output Update Rate
	500	Hz max nom	
No Missing Codes ²	24	Bits min	f _{ADC} ≤125 Hz
Resolution	15.5	Bits p-p	Gain = 128, 16.6 Hz Update Rate, V _{REF} = 2.5 V
	18.5	Bits p-p	Gain = 1, 16.6 Hz Update Rate, V _{REF} = 2.5 V
Output Noise and Update Rates	See Tables in ADC Description		
Integral Nonlinearity	±15	ppm of FSR max	3.5 ppm of FSR typ. Gain = 1 to 32
	±25	ppm of FSR max	5 ppm of FSR typ, Gain = 64 or 128
Offset Error ³	±200/Gain	μV typ	Without Calibration
Offset Error Drift vs. Temperature ⁴	±200/Gain	nV/°C typ	
Full-Scale Error ^{3, 5}	±10	μV typ	
Gain Drift vs. Temperature ⁴	±0.5	ppm/°C typ	Gain = 1 or 2
p	±3	ppm/°C typ	Gain = 4 to 128
Power Supply Rejection	80	dB min	100 dB typ, AIN = FS/2
ANALOG INPUTS			100 at 9/4/1 at 10/2
Differential Input Voltage Ranges	±REFIN/Gain	V nom	REFIN = REFIN(+) – REFIN(–) or Internal Reference Gain = 1 to 128
Absolute AIN Voltage Limits ²			
Unbuffered Mode	GND – 30 mV	V min	Gain = 1 or 2
	$AV_{DD} + 30 \text{ mV}$	V max	
Buffered Mode	GND + 100 mV	V min	Gain = 1 or 2
	AV _{DD} – 100 mV	V max	
In-Amp Enabled	GND + 100 mV	V min	Gain = 4 to 128
·	AV _{DD} – 1.1	V max	
Common Mode Voltage	0.5	V min	Gain = 4 to 128
Analog Input Current			
Buffered Mode or In-Amp Enabled			
Average Input Current ²	±200	pA max	
Average Input Current Drift	±2	pA/°C typ	
Unbuffered Mode		P. v 5/P	Gain = 1 or 2
Average Input Current	±400	nA/V typ	Input current varies with input voltage.
Average Input Current Drift	±50	pA/V/°C typ	input current varies with input voltage.
Average input current Dine	1	nA max	AIN6(+) / AIN6(-)
Normal Mode Rejection ²		IIAIIIAX	Allvo(+) / Allvo(-)
Internal Clock			
@ 50 Hz, 60 Hz	60	dB min	70 dB typ, 50 ± 1 Hz, 60 ± 1 Hz, $FS[3:0] = 1010^6$
@ 50 Hz	80	dB min	90 dB typ, 50 ± 1 Hz, $FS[3:0] = 1001^6$
@ 60 Hz	90	dB min	100 dB typ, 60 ± 1 Hz, FS[3:0] = 1000^6
External Clock	90	UB IIIIII	100 db typ, 00 ± 1 Hz, F3[3.0] = 1000
	60	dB min	70 dP + 10 F0 + 1 H= 60 + 1 H= F5[2:0] = 10106
@ 50 Hz, 60 Hz	60		70 dB typ, 50 ± 1 Hz, 60 ± 1 Hz, $FS[3:0] = 1010^6$
@ 50 Hz	94	dB min	100 dB typ, 50 ± 1 Hz, FS[3:0] = 1001 ⁶
@ 60 Hz	90	dB min	100 dB typ, 60 ± 1 Hz, FS[3:0] = 1000^6
Common Mode Rejection	00	alD main	AIN = +FS/2
@DC	80	dB min	FS[3:0] = 1010 ⁶
@ 50 Hz, 60 Hz ²	80	dB min	50 ± 1 Hz, 60 ± 1 Hz, FS[3:0] = 1010^6
@ 50 Hz, 60 Hz ²	80	dB min	50 ± 1 Hz (FS[3:0] = 10016), 60 ± 1 Hz (FS[3:0] = 10006)
REFERENCE INPUT			
Internal Reference Initial Accuracy	1.17 ±0.01%	V min/max	
Internal Reference Drift	5	ppm/°C typ	
	15	ppm/°C max	

Parameter	AD7794B	Unit	Test Conditions/Comments	
Internal Reference Noise	2	μV RMS	Gain = 1, Update Rate = 16.6 Hz. Includes ADC Noise.	
External REFIN Voltage	2.5	V nom	REFIN = REFIN(+) - REFIN(-)	
Reference Voltage Range ²	0.1	V min		
	V _{DD}	V max		
Absolute REFIN Voltage Limits ²	GND – 30 mV	V min		
	$AV_{DD} + 30 \text{ mV}$	V max		
Average Reference Input Current	400	nA/V typ		
Average Reference Input Current Drift	±0.03	nA/V/°C typ		
Normal Mode Rejection ²	Same as for Analog Inputs			
Common Mode Rejection	Same as for Analog Inputs			
Reference Detect Levels	0.3	V min	NOXREF Bit Inactive if VREF < 0.3 V	
	0.65	V max	NOXREF Bit Active if VREF > 0.65 V	

Parameter	AD7794B	Unit	Test Conditions/Comments
EXCITATION CURRENT SOURCES (IEXC1 ar	nd IEXC2)	· · · · · · · · · · · · · · · · · · ·	
Output Current	10/200/1000	μA nom	
Initial Tolerance at 25°C	±5	% typ	
Drift	200	ppm/°C typ	
Initial Current Matching at 25°C	±1	% typ	Matching between IEXC1 and EXC2. Vout = 0 V
Drift Matching	20	ppm/°C typ	
Line Regulation (V _{DD})	2.1	ppm/V max	$AV_{DD} = 5 \text{ V} \pm 5\%$. Typically 1.25 ppm/V
Load Regulation	0.3	ppm/V typ	, , , , , , , , , , , , , , , , , , ,
Output Compliance	AV _{DD} – 0.6	V max	Current Sources Programmed to 10 μA or 200 μA
output compliance	AV _{DD} – 1	V max	Current Sources Programmed to 1 mA
	GND – 30 mV	V min	current sources rrogrammed to r mix
BIAS VOLTAGE GENERATOR	GIVE SO IIIV	V 111111	
V _{BIAS}	AV _{DD} /2	V nom	
V _{BIAS} Generator Start-Up Time	TBD	ms/nF typ	Dependent on the Capacitance connected to AIN
TEMPERATURE SENSOR	TBD	IIIs/IIF typ	Dependent on the Capacitance connected to Air
	TBD	°C tup	
Accuracy	וסט	°C typ	
LOW SIDE POWER SWITCH	-		AV 5.V
Ron	5	Ω max	$AV_{DD} = 5 V$
	7	Ω max	$AV_{DD} = 3 V$
Allowable Current	20	mA max	Continuous Current
DIGITAL OUTPUTS (P1 & P2)			
V _{OH} , Output High Voltage ²	AV _{DD} – 0.6	V min	$AV_{DD} = 3 \text{ V}$, $I_{SOURCE} = 100 \mu A$
Vol., Output Low Voltage ²	0.4	V max	$AV_{DD} = 3 \text{ V}, I_{SINK} = 100 \mu A$
V _{OH} , Output High Voltage ²	4	V min	$AV_{DD} = 5 \text{ V, } I_{SOURCE} = 200 \mu A$
V _{OL} , Output Low Voltage ²	0.4	V max	$AV_{DD} = 5 \text{ V}, I_{SINK} = 800 \mu A$
Floating-State Leakage Current	±1	μA max	
Floating-State Output Capacitance	10	pF typ	
INTERNAL/EXTERNAL CLOCK			
Internal Clock			
Fequency	64 ±2%	64 ±2%	
Duty Cycle	50:50	50:50	
Drift	0.01	0.01	
External Clock	0.01	0.01	
Frequency	64	64	
Duty Cycle	45:55	45:55	
LOGIC INPUTS	45.55	75.55	
All Inputs Except SCLK, DIN and CLK ²			
V _{INL} , Input Low Voltage	0.8	V max	$DV_{DD} = 5 V$
V _{INL} , IIIput Low Voltage			
V Income I Barb Malkania	0.4	V max	$DV_{DD} = 3V$
V _{INH} , Input High Voltage	2.0	V min	$DV_{DD} = 3 \text{ V or } 5 \text{ V}$
SCLK and DIN (Schmitt-Triggered Input) ²			
V _T (+)	1.4/2	V min/V max	$DV_{DD} = 5 V$
V _T (-)	0.8/1.4	V min/V max	$DV_{DD} = 5 V$
$V_{T}(+) - V_{T}(-)$	0.3/0.85	V min/V max	$DV_{DD} = 5 V$
V _T (+)	0.9/2	V min/V max	$DV_{DD} = 3 V$
V _τ (-)	0.4/1.1	V min/V max	$DV_{DD} = 3 V$
$V_T(+) - V_T(-)$	0.3/0.85	V min/V max	$DV_{DD} = 3 V$
CLK ²			
V _{INL} , Input Low Voltage	0.8	V max	$DV_{DD} = 5 V$
V _{INL} , Input Low Voltage	0.4	V max	$DV_{DD} = 3 V$
V _{INH} , Input High Voltage	3.5	V min	$DV_{DD} = 5 V$

Parameter	AD7794B	Unit	Test Conditions/Comments	
V _{INH} , Input High Voltage	2.5	V min	$DV_{DD} = 3 V$	
Input Currents	±1	μA max	$V_{IN} = DV_{DD}$ or GND	
Input Capacitance	10	pF typ	All Digital Inputs	
LOGIC OUTPUTS (Including CLK)				
V _{OH} , Output High Voltage ²	DV _{DD} - 0.6	V min	$DV_{DD} = 3 \text{ V, } I_{SOURCE} = 100 \mu\text{A}$	
V _{OL} , Output Low Voltage ²	0.4	V max	$DV_{DD} = 3 \text{ V, } I_{SINK} = 100 \mu\text{A}$	
V _{OH} , Output High Voltage ²	4	V min	$DV_{DD} = 5 \text{ V, } I_{SOURCE} = 200 \mu\text{A}$	
V _{OL} , Output Low Voltage ²	0.4	V max	$DV_{DD} = 5 \text{ V}$, $I_{SINK} = 1.6 \text{ mA} (DOUT/\overline{RDY})/800 \mu A (CLK)$	
Floating-State Leakage Current	±1	μA max		
Floating-State Output Capacitance	10	pF typ		
Data Output Coding	Offset Binary			
SYSTEM CALIBRATION ²		V max		
Full-Scale Calibration Limit	1.05 x FS	V max		
Zero-Scale Calibration Limit	-1.05 x FS	V min		
Input Span	0.8 x FS	V min		
	2.1 x FS	V min		
POWER REQUIREMENTS ⁷				
Power Supply Voltage				
$AV_{DD} - GND$	2.7/5.25	V min/max		
$DV_{DD} - GND$	2.7/5.25	V min/max		
Power Supply Currents				
I _{DD} Current	150	μA max	125 μA typ, Unbuffered Mode, Ext. Reference	
	175	μA max	150 μA typ, Buffered Mode, In-Amp Bypassed, Ext Ref	
	380	μA max	330 μA typ, In-Amp used, Ext. Ref	
	450	μA max	400 μA typ, In-Amp used, Int Ref	
I _{DD} (Power-Down Mode)	1	μA max		

¹ Temperature Range –40°C to +105°C. ² Specification is not production tested but is supported by characterization data at initial product release. ³ Following a self-calibration, this error will be in the order of the noise for the programmed gain and update rate selected. A system calibration will completely remove

⁴ Recalibration at any temperature will remove these errors.
⁵ Full-scale error applies to both positive and negative full-scale and applies at the factory calibration conditions (AV_{DD} = 4 V).

⁶ FS[3:0] are the four bits used in the mode register to select the output word rate.

 $^{^7}$ Digital inputs equal to $\mathsf{DV}_{\mathsf{DD}}$ or GND.

TIMING CHARACTERISTICS8,9

Table 2. $(AV_{DD} = 2.7 \text{ V to } 5.25 \text{ V}; DV_{DD} = 2.7 \text{ V to } 5.25; GND = 0 \text{ V}, Input Logic 0 = 0 \text{ V}, Input Logic 1 = DV_{DD}, unless otherwise noted.)$

Parameter	Limit at T _{MIN} , T _{MAX} (B Version)	Unit	Conditions/Comments
t ₃	100	ns min	SCLK High Pulsewidth
t ₄	100	ns min	SCLK Low Pulsewidth
Read Operation			
t_1	0	ns min	CS Falling Edge to DOUT/RDY Active Time
	60	ns max	$DV_{DD} = 4.75 \text{ V to } 5.25 \text{ V}$
	80	ns max	$DV_{DD} = 2.7 \text{ V to } 3.6 \text{ V}$
t_2^{10}	0	ns min	SCLK Active Edge to Data Valid Delay ¹¹
	60	ns max	$DV_{DD} = 4.75 \text{ V to } 5.25 \text{ V}$
	80	ns max	$DV_{DD} = 2.7 \text{ V to } 3.6 \text{ V}$
t ₅ ^{12, 13}	10	ns min	Bus Relinquish Time after CS Inactive Edge
	80	ns max	
t_6	100	ns max	SCLK Inactive Edge to CS Inactive Edge
t ₇	10	ns min	SCLK Inactive Edge to DOUT/RDY High
Write Operation			
t ₈	0	ns min	CS Falling Edge to SCLK Active Edge Setup Time ¹¹
t ₉	30	ns min	Data Valid to SCLK Edge Setup Time
t ₁₀	25	ns min	Data Valid to SCLK Edge Hold Time
t ₁₁	0	ns min	CS Rising Edge to SCLK Edge Hold Time

⁸ Sample tested during initial release to ensure compliance. All input signals are specified with $t_R = t_F = 5$ ns (10% to 90% of DV_{DD}) and timed from a voltage level of 1.6 V.

⁹ See Figure 2 and Figure 3.

¹⁰ These numbers are measured with the load circuit of

Figure 1 and defined as the time required for the output to cross the V_{OL} or V_{OH} limits.

¹¹ SCLK active edge is falling edge of SCLK.

¹² These numbers are derived from the measured time taken by the data output to change 0.5 V when loaded with the circuit of

Figure 1. The measured number is then extrapolated back to remove the effects of charging or discharging the 50 pF capacitor. This means that the times quoted in the timing characteristics are the true bus relinquish times of the part and, as such, are independent of external bus loading capacitances.

¹³ RDY returns high after a read of the ADC. In single conversion mode and continuous conversion mode, the same data can be read again, if required, while RDY is high, although care should be taken to ensure that subsequent reads do not occur close to the next output update. In continuous read mode, the digital word can be read only once.

ISINK (1.6 mA WITH DVDD = 5V, 100
$$\mu$$
A WITH DVDD = 3V)

TO OUTPUT PINO 0+1.6 V

SOURCE (200 μ A WITH DVDD = 5V, 100 μ A WITH DVDD = 5V, 100 μ A WITH DVDD = 3V)

Figure 1. Load Circuit for Timing Characterization

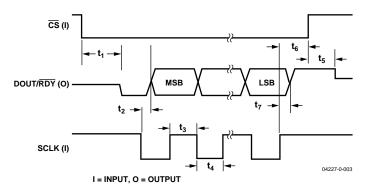


Figure 2. Read Cycle Timing Diagram

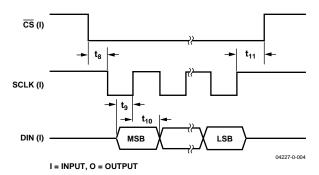


Figure 3. Write Cycle Timing Diagram

ABSOLUTE MAXIMUM RATINGS

Table 3. ($T_A = 25^{\circ}C$, unless otherwise noted.)

Table 5. (TA= 25 C, diffess otherwise i	101011)
Parameter	Rating
AV _{DD} to GND	–0.3 V to +7 V
DV _{DD} to GND	-0.3 V to +7 V
Analog Input Voltage to GND	$-0.3 \text{ V to AV}_{DD} + 0.3 \text{ V}$
Reference Input Voltage to GND	$-0.3 \text{ V to AV}_{DD} + 0.3 \text{ V}$
Digital Input Voltage to GND	$-0.3 \text{ V to AV}_{DD} + 0.3 \text{ V}$
Digital Output Voltage to GND	$-0.3 \text{ V toA V}_{DD} + 0.3 \text{ V}$
AIN/Digital Input Current	10 mA
Operating Temperature Range	-40°C to +105°C
Storage Temperature Range	−65°C to +150°C
Maximum Junction Temperature	150°C
TSSOP	
θ_{JA} Thermal Impedance	97.9°C/W
θ_{JC} Thermal Impedance	14°C/W
Lead Temperature, Soldering	
Vapor Phase (60 sec)	215°C
Infrared (15 sec)	220°C

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although this product features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

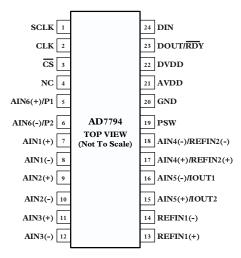


Figure 4. Pin Configuration

Table 4. Pin Function Descriptions

	e 4. Pin Function I	rescriptions
Pin		
No.	Mnemonic	Function
1	SCLK	Serial Clock Input for Data Transfers to and from the ADC. The SCLK has a Schmitt-triggered input, making the interface suitable for opto-isolated applications. The serial clock can be continuous with all data transmitted in a continuous train of pulses. Alternatively, it can be a noncontinuous clock with the information being transmitted to or from the ADC in smaller batches of data.
2	CLK	Clock In/Clock Out. The internal clock can be made available at this pin. Alternatively, the internal clock can be disabled and the ADC can be driven by an external clock. This allows several ADCs to be driven from a common clock, allowing simultaneous conversions to be performed.
3	टड	Chip Select Input. This is an active low logic input used to select the ADC. \overline{CS} can be used to select the ADC in systems with more than one device on the serial bus or as a frame synchronization signal in communicating with the device. \overline{CS} can be hardwired low, allowing the ADC to operate in 3-wire mode with SCLK, DIN, and DOUT used to interface with the device.
4	NC	No Connect
5	AIN6(+)/P1	Analog Input/Digital Output pin. AIN6(+) is the positive terminal of the differential analog input pair AIN6(+)/AIN6(-). Alternatively, this pin can function as a general purpose output bit referenced between AV _{DD} and GND
6	AIN6(-)/P2	Analog Input/ Digital Output pin. AIN6(–) is the negative terminal of the differential analog input pair AIN6(+)/AIN6(-). Alternatively, this pin can function as a general purpose output bit referenced between AV _{DD} and GND
7	AIN1(+)	Analog Input. AIN1(+) is the positive terminal of the differential analog input pair AIN1(+)/AIN1(-).
8	AIN1(-)	Analog Input. AIN1(–) is the negative terminal of the differential analog input pair AIN1(+)/AIN1(-).
9	AIN2(+)	Analog Input. AIN2(+) is the positive terminal of the differential analog input pair AIN2(+)/AIN2(-).
10	AIN2(-)	Analog Input. AIN2(–) is the negative terminal of the differential analog input pair AIN2(+)/AIN2(-).
11	AIN3(+)	Analog Input. AIN3(+) is the positive terminal of the differential analog input pair AIN3(+)/AIN3(-).
12	AIN3(-)	Analog Input. AIN3(–) is the negative terminal of the differential analog input pair AIN3(+)/AIN3(-).
13	REFIN1(+)	Positive Reference Input. An external reference can be applied between REFIN1(+) and REFIN1(-). REFIN1(+) can lie anywhere between V_{DD} and GND + 0.1 V. The nominal reference voltage (REFIN1(+) – REFIN1(-)) is 2.5 V, but the part functions with a reference from 0.1 V to AV_{DD} .
14	REFIN1(-)	Negative Reference Input. This reference input can lie anywhere between GND and AV _{DD} – 0.1 V.
15	AIN5(+)/IOUT2	Analog Input/Output of Internal Excitation Current Source.
		AIN5(+) is the positive terminal of the differential analog input pair AIN5(+)/AIN5(-).
		Alternatively, the internal excitation current source can be made available at this pin. The excitation current source is programmable so that the current can be 10 uA, 200 uA or 1 mA. Either IEXC1 or IEXC2 can be switched to this output
16	AIN5(-)/IOUT1	Analog Input/Output of Internal Excitation Current Source.

Pin No.	Mnemonic	Function
		AIN5(-) is the negative terminal of the differential analog input pair AIN5(+)/AIN5(-).
		Alternatively, the internal excitation current source can be made available at this pin. The excitation current source is programmable so that the current can be 10 uA, 200 uA or 1 mA. Either IEXC1 or IEXC2 can be switched to this output.
17	AIN4(+)/REFIN2(+)	Analog Input/Positive Reference Input.
		AIN4(+) is the positive terminal of the differential analog input pair AIN4(+)/AIN4(-).
		This pin can aso function as a reference input. REFIN2(+) can lie anywhere between AV _{DD} and GND + 0.1 V. The nominal reference voltage (REFIN2(+) – REFIN2(–)) is 2.5 V, but the part functions with a reference from 0.1 V to AV _{DD} .
18	AIN4(-)/REFIN2(-)	Analog Input/Negative Reference Input.
		AIN4(-) is the negative terminal of the differential analog input pair AIN4(+)/AIN4(-).
		This pin also functions as the negative reference input for REFIN2. This reference input can lie anywhere between GND and $AV_{DD} - 0.1 \text{ V}$.
19	PSW	Low Side Power Switch to GND.
20	GND	Ground Reference Point.
21	AV _{DD}	Supply Voltage, 2.7 V to 5.25 V.
22	D V _{DD}	Serial Interface Supply Voltage, 2.7 V to 5.25 V. DV_{DD} is independent of AV_{DD} . Therefore, the serial interface can be operated at 3 V with AV_{DD} at 5 V or vice versa.
23	DOUT/RDY	Serial Data Output/Data Ready Output. DOUT/RDY serves a dual purpose. It functions as a serial data output pin to access the output shift register of the ADC. The output shift register can contain data from any of the on-chip data or control registers. In addition, DOUT/RDY operates as a data ready pin, going low to indicate the completion of a conversion. If the data is not read after the conversion, the pin will go
		high before the next update occurs.
		The DOUT/RDY falling edge can be used as an interrupt to a processor, indicating that valid data is available. With an external serial clock, the data can be read using the DOUT/RDY pin. With CS low, the data/control word informa-tion is placed on the DOUT/RDY pin on the SCLK falling edge and is valid on the SCLK rising edge.
		The end of a conversion is also indicated by the RDY bit in the status register. When CS is high, the DOUT/RDY pin is three-stated but the RDY bit remains active.
24	DIN	Serial Data Input to the Input Shift Register on the ADC. Data in this shift register is transferred to the control registers within the ADC, the register selection bits of the communications register identifying the appropriate register.

TYPICAL PERFORMANCE CHARACTERISTICS

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Figure 5.		Figure 8.
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Figure 6.		Figure 9.
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Figure 7. Figure 10.

ON-CHIP REGISTERS

The ADC is controlled and configured via a number of on-chip registers, which are described on the following pages. In the following descriptions, *set* implies a Logic 1 state and *cleared* implies a Logic 0 state, unless otherwise stated.

COMMUNICATIONS REGISTER (RS2, RS1, RS0 = 0, 0, 0)

The communications register is an 8-bit write-only register. All communications to the part must start with a write operation to the communications register. The data written to the communications register determines whether the next operation is a read or write operation, and to which register this operation takes place. For read or write operations, once the subsequent read or write operation to the selected register is complete, the interface returns to where it expects a write operation to the communications register. This is the default state of the interface and, on power-up or after a reset, the ADC is in this default state waiting for a write operation to the communications register. In situations where the interface sequence is lost, a write operation of at least 32 serial clock cycles with DIN high returns the ADC to this default state by resetting the entire part. Table 5 outlines the bit designations for the communications register. CR0 through CR7 indicate the bit location, CR denoting the bits are in the communications register. CR7 denotes the first bit of the data stream. The number in brackets indicates the power-on/reset default status of that bit.

CR7	CR6	CR5	CR4	CR3	CR2	CR1	CR0
WEN(0)	R/W(0)	RS2(0)	RS1(0)	RS0(0)	CREAD(0)	0(0)	0(0)

Table 5. Communications Register Bit Designations

Bit Location	Bit Name	Description
CR7	WEN	Write Enable Bit. A 0 must be written to this bit so that the write to the communications register actually occurs. If a 1 is the first bit written, the part will not clock on to subsequent bits in the register. It will stay at this bit location until a 0 is written to this bit. Once a 0 is written to the WEN bit, the next seven bits will be loaded to the communications register.
CR6	R/W	A 0 in this bit location indicates that the next operation will be a write to a specified register. A 1 in this position indicates that the next operation will be a read from the designated register.
CR5-CR3	RS2-RS0	Register Address Bits. These address bits are used to select which of the ADC's registers are being selected during this serial interface communication. See Table 6.
CR2	CREAD	Continuous Read of the Data Register. When this bit is set to 1 (and the data register is selected), the serial interface is configured so that the data register can be continuously read, i.e., the contents of the data register are placed on the DOUT pin automatically when the SCLK pulses are applied. The communications register does not have to be written to for data reads. To enable continuous read mode, the instruction 01011100 must be written to the communications register. To exit the continuous read mode, the instruction 01011000 must be written to the communications register while the RDY pin is low. While in continuous read mode, the ADC monitors activity on the DIN line so that it can receive the instruction to exit continuous read mode. Additionally, a reset will occur if 32 consecutive 1s are seen on DIN. Therefore, DIN should be held low in continuous read mode until an instruction is to be written to the device.
CR1-CR0	0	These bits must be programmed to logic 0 for correct operation.

Table 6. Register Selection

RS2	RS1	RS0	Register	Register Size
0	0	0	Communications Register during a Write Operation	8-Bit
0	0	0	Status Register during a Read Operation	8-Bit
0	0	1	Mode Register	16-Bit
0	1	0	Configuration Register	16-Bit
0	1	1	Data Register	24-Bit
1	0	0	ID Register	8-Bit
1	0	1	IO Register	8-Bit
1	1	0	Offset Register	24-Bit
1	1	1	Full-ScaleRegister	24-Bit

STATUS REGISTER (RS2, RS1, RS0 = 0, 0, 0; POWER-ON/RESET = 0x88)

The status register is an 8-bit read-only register. To access the ADC status register, the user must write to the communications register, select the next operation to be a read, and load bits RS2, RS1 and RS0 with 0. Table 7 outlines the bit designations for the status register. SR0 through SR7 indicate the bit locations, SR denoting the bits are in the status register. SR7 denotes the first bit of the data stream. The number in brackets indicates the power-on/reset default status of that bit.

SR7	SR6	SR5	SR4	SR3	SR2	SR1	SR0
RDY(1)	ERR(0)	NOREF(0)	0(0)	1(1)	CH2(0)	CH1(0)	CH0(0)

Table 7. Status Register Bit Designations

Bit Location	Bit Name	Description
SR7	RDY	Ready bit for ADC. Cleared when data is written to the ADC data register. The RDY bit is set automatically after the ADC data register has been read or a period of time before the data register is updated with a new conversion result to indicate to the user not to read the conversion data. It is also set when the part is placed in power-down mode. The end of a conversion is indicated by the DOUT/RDY pin also. This pin can be used as an alternative to the status register for monitoring the ADC for conversion data.
SR6	ERR	ADC Error Bit. This bit is written to at the same time as the RDY bit. Set to indicate that the result written to the ADC data register has been clamped to all 0s or all 1s. Error sources include overrange, underrange or the absence of a reference voltage. Cleared by a write operation to start a conversion.
SR5	NOREF	No External Reference Bit. Set to indicate that the selected reference (REFIN1 or REFIN2) is at a voltage that is below a specified threshold. When set, conversion results are clamped to all ones.
		Cleared to indicate that a valid reference is applied to the selected reference pins.
		The NOXREF bit is enabled by setting the REF_DET bit in the Configuration register to 1. The ERR bit is also set if the voltage applied to the selected reference input is invalid.
SR4	0	This bit is automatically <i>cleared</i> .
SR3	1	This bit is automatically set.
SR2-SR0	CH2-CH0	These bits indicate which channel is being converted by the ADC.

MODE REGISTER (RS2, RS1, RS0 = 0, 0, 1; POWER-ON/RESET = 0×0000 A)

The mode register is a 16-bit register from which data can be read or to which data can be written. This register is used to select the operating mode, the update rate and the clock source. Table 8 outlines the bit designations for the mode register. MR0 through MR15 indicate the bit locations, MR denoting the bits are in the mode register. MR15 denotes the first bit of the data stream. The number in brackets indicates the power-on/reset default status of that bit. Any write to the setup register resets the modulator and filter and sets the RDY bit.

MR15	MR14	MR13	MR12	MR11	MR10	MR9	MR8
MD2(0)	MD1(0)	MD0(0)	PSW(0)	0(0)	0(0)	0(0)	0(0)
MR7	MR6	MR5	MR4	MR3	MR2	MR1	MRO
CLK1(0)	CLK0(0)	0(0)	CHOP-DIS (0)	FS3(1)	FS2(0)	FS1(1)	FS0(0)

Table 8. Mode Register Bit Designations

Bit Location	Bit Name	Description
MR15-MR13	MD2-MD0	Mode Select Bits. These bits select the operational mode of the AD7794 (See
		Table 9).
MR12	PSW	Power Switch Control Bit.
		Set by user to close the power switch PSW to GND. The power switch can sink up to 20 mA.
		Cleared by user to open the power switch.
		When the ADC is placed in power-down mode, the power switch is opened.
MR11-MR8	0	These bits must be programmed with a Logic 0 for correct operation.
MR7-MR6	CLK1-CLK0	These bits are used to select the clock source for the AD7794. Either the on-chip 64 kHz clock can be used or an external clock can be used. The ability to use an external clock is useful as it allows several AD7794 devices to be synchronised. Also, 50 Hz/60 Hz rejection is improved when an accurate external clock drives the AD7794.

Bit Location	Bit Name	Description				
		CLK1	CLK0	ADC Clock Source		
		0	0	Internal 64 kHz Clock, Internal Clock is not available at the CLK pin		
		0	1	Internal 64 kHz Clock. This clock is made available at the CLK pin		
		1	0	External 64 kHz Clock used. The external clock can have a 45:55 duty cycle.		
		1	1	External Clock used. This external clock is divided by 2 within the AD7794. This allows the user to supply a clock which has a duty cycle worse than a 45:55 duty cycle to the AD7794, for example, a 128 kHz clock.		
MR5	0	This bit i	nust be	programmed with a Logic 0 for correct operation.		
MR4	CHOP-DIS		This bit is used to enable or disable chopping. On power-up or following a reset, CHOP-DIS is cleared so chopping is enabled. When CHOP-DIS is set, chopping is disabled.			
MR3-MR0	FS3-FS0	Filter Up	Filter Update Rate Select Bits (see Table 10).			

Table 9. Operating Modes

MD2	MD1	MD0	Mode
0	0	0	Continuous Conversion Mode (Default).
			In continuous conversion mode, the ADC continuously performs conversions and places the result in the data register. RDY goes low when a conversion is complete. The user can read these conversions by placing the
			device in continuous read mode whereby the conversions are automatically placed on the DOUT line when SCLK pulses are applied. Alternatively, the user can instruct the ADC to output the conversion by writing to the communications register. After power-on, the first conversion is available after a period $2/f_{ADC}$ when chopping is enabled or $1/f_{ADC}$ when chopping is disabled. Subsequent conversions are available at a frequency of f_{ADC} with chopping either enabled or disabled,
0	0	1	Single Conversion Mode.
			In single conversion mode, the ADC is placed in power-down mode when conversions are not being performed. When single conversion mode is selected, the ADC powers up and performs a single conversion, which occurs after a period 2/f _{ADC} when chopping is enabled or 1/f _{ADC} when chopping is disabled. The conversion result in placed in the data register, RDY goes low, and the ADC returns to power-down mode. The conversion remains in the data register and RDY remains active (low) until the data is read or another conversion is performed.
0	1	0	Idle Mode.
			In Idle Mode, the ADC Filter and Modulator are held in a reset state although the modulator clocks are still provided
0	1	1	Power-Down Mode.
			In power down mode, all the AD7794 circuitry is powered down including the current sources, power switch, burnout currents, bias voltage generator and CLKOUT circuitry.
1	0	0	Internal Zero-Scale Calibration.
			An internal short is automatically connected to the enabled channel. A calibration takes 2 conversion cycles to complete when chopping is enabled and 1 conversion cycle when chopping is disabled. RDY goes high when the calibration is initiated and returns low when the calibration is complete. The ADC is placed in idle mode following a calibration. The measured offset coefficient is placed in the offset register of the selected channel
1	0	1	Internal Full-Scale Calibration.
			The fullscale input voltage is automatically connected to the selected analog input for this calibration.
			The full-scale error of the AD7794 is calbrated at a gain of 1 using the internal reference in the factory. When a channel is operated with a gain of 1 and the internal reference is selected, this factory-calibrated value is loaded into the full-scale register when a full-scale calibration is initiated.
			When an external reference is selected at a gain of 1, an internal fullscale calibration can be performed. When the gain equals 1, a calibration takes 2 conversion cycles to complete when chopping is enabled and 1 conversion cycle when chopping is disabled.
			For higher gains, 4 conversion cycles are required to perform the fullscale calibration when chopping is enabled and 2 conversion cycles when chopping is disabled.
			RDY goes high when the calibration is initiated and returns low when the calibration is complete. The ADC is placed in idle mode following a calibration. The measured fullscale coefficient is placed in the fullscale register of the selected channel.
			Internal full-scale calibrations cannot be performed when the gain equals 128. With this gain setting, a system full-scale calibration can be performed.

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1	1	0	A fullscale calibration is required each time the gain of a channel is changed. System Offset Calibration.
			User should connect the system zero-scale input to the .channel input pins as selected by the CH2-CH0 bits. A system offset calibration takes 2 conversion <u>cycles</u> to complete when chopping is enabled and one conversion cycle when chopping is disabled. RDY goes high when the calibration is initiated and returns low when the calibration is complete. The ADC is placed in idle mode following a calibration. The measured offset coefficient is placed in the offset register of the selected channel.
1	1	1	System Full-Scale Calibration.
			User should connect the system full-scale input to the .channel input pins as selected by the CH2-CH0 bits.
			A calibration takes 2 conversion cycles to complete when chopping is enabled and one conversion cycle when chopping is disabled RDY goes high when the calibration is initiated and returns low when the calibration is complete. The ADC is placed in idle mode following a calibration. The measured fullscale coefficient is placed in the fullscale register of the selected channel.
			A fullscale calibration is required each time the gain of a channel is changed.

Table 10. Update Rates Available (Chopping Enabled)

					Tsettle	
FS3	FS2	FS1	FS0	f _{ADC} (Hz)	(ms)	Rejection@ 50 Hz / 60 Hz (Internal Clock)
0	0	0	0	х	х	
0	0	0	1	500	5	
0	0	1	0	250	8	
0	0	1	1	125	16	
0	1	0	0	62.5	32	
0	1	0	1	50	40	
0	1	1	0	41.6	48	
0	1	1	1	33.3	60	
1	0	0	0	19.6	101	90 dB (60 Hz only)
1	0	0	1	16.6	120	84 dB (50 Hz only)
1	0	1	0	16.6	120	70 dB (50 Hz and 60 Hz)
1	0	1	1	12.5	160	67 dB (50 Hz and 60 Hz)
1	1	0	0	10	200	69 dB (50 Hz and 60 Hz)
1	1	0	1	8.33	240	73 dB (50 Hz and 60 Hz)
1	1	1	0	6.25	320	74 dB (50 Hz and 60 Hz)
1	1	1	1	4.17	480	79 dB (50 Hz and 60 Hz)

With chopping disabled, the update rates remain unchanged but the settling time for each update rate is reduced by a factor of 2. The rejection at 50 Hz/60 Hz for a 16.6 Hz update rate degrades to 60 dB.

CONFIGURATION REGISTER (RS2, RS1, RS0 = 0, 1, 0; POWER-ON/RESET = 0x0710)

The configuration register is a 16-bit register from which data can be read or to which data can be written. This register is used to configure the ADC for unipolar or bipolar mode, enable or disable the buffer, enable or disable the burnout currents, select the gain and select the analog input channel. Table 11 outlines the bit designations for the filter register. CON0 through CON15 indicate the bit locations, CON denoting the bits are in the configuration register. CON15 denotes the first bit of the data stream. The number in brackets indicates the power-on/reset default status of that bit.

CON15	CON14	CON13	CON12	CON11	CON10	CON9	CON8
VBIAS1(0)	VBIASO(0)	BO(0)	U/B (0)	0(0)	G2(1)	G1(1)	G0(1)
CON7	CON6	CON5	CON4	CON3	CON2	CON1	CON0

Table 11. Configuration Register Bit Designations

Table 11.	Configuration Reg	ister Bit l	Desig	nations						
Bit Location	Bit Name	Description								
CON15-	0	Bias Vol	tage (Generato	r Enab	nable. The negative terminal of the analog inputs can be biased up to VDD/2.				
CON14	CON14			VBIAS0	В	Bias Voltage				
		0 0		В	ias Voltage Genera	tor Disa	bled			
		0	0 1		В	ias Voltage Genera	itor coni	nected to AIN1(-)		
		1	1 0		В	ias Voltage Genera	itor coni	nected to AIN2(-)		
		1		1	В	ias Voltage Genera	itor coni	nected to AIN3(-)		
CON13	ВО	This bit	must	be progr		ed with a Logic 0 fo				
		Burnou path are	t Curre e enab	ent Enabl led. Whe	e Bit. en BO	When this bit is set	t to 1 by	the user, the 100 nA current sources in the signal are disabled. The burnout currents can be enabled		
CON12	U/B	0x000000 output and a fenable bipolar coding. No zero differential input winput will result in an ou			a full- . Nega will re output	by user to enable unipolar coding, i.e., zero differential input will result in full-scale differential input will result in 0xFFFFFF output. Cleared by the user to legative full-scale differential input will result in an output code of 0x000000, ill result in an output code of 0x800000, and a positive full-scale differential tput code of 0xFFFFFF.				
CON11	0	This bit	must	be progr	amme	ed with a Logic 0 fo	or correc	t operation.		
CON10-	G2-G0	Gain Se								
CON8		Written	by th	e user to	select	the ADC input ran	ige as fo	ollows		
		G2	G1	G0	Gai	n	ADC I	nput Range (2.5V Reference)		
		0	0	0	1 (Ir	n-Amp not used)	2.5 V			
		0	0	1	2 (Ir	n-Amp not used)	1.25 V	1		
		0	1	0	4		625 m	nV		
		0	1	1	8		312.5	mV		
		1	0	0	16		156.2	mV		
		1	0	1	32		78.125	5 mV		
		1	1	0	64		39.06			
		1	1	1	128		19.53			
CON7-	REFSEL1/REFSEL0		_					C is selected using these bits.		
CON7-	NEI SEEI/NEI SEEO					eference Source	the AD	C is selected using these bits.		
		0	LI	0			applied	between REFIN1(+) and REFIN1(-)		
		0		1			• •	between REFIN2(+) and REFIN2(-)		
		1		0		nternal 1.17 V Refer	• • • • • • • • • • • • • • • • • • • •	between KEI INZ(+) and KEI INZ(-)		
		 ' 1		1		eserved	ence			
				-	10	eserveu				
CON5	REF_DET	Enables the Reference Detect Function. When <i>set</i> , the NOXREF bit in the status register indicates when the external reference being use ADC is open circuit or less than 0.5 V. When <i>cleared</i> , the reference detect function is disabled.								
CON4	BUF		Configures the ADC for buffered or unbuffered mode of operation. If <i>cleared</i> , the ADC operates in							
		unbuffe mode, a to the st automa	ered mallowir ystem tically	ode, low ng the us . For gair enabled	ering er to p ns of 1	the power consum place source imped	of the device. If set, the ADC operates in buffered on the front end without contributing gain errors nabled or disabled. For higher gains, the buffer is			
CON3- CON0	CH3-CH0	Channe			- ماء -	the estimates as	ا. عنصما	aannal ta tha ADC		
CONO				_		the active analog	input ch			
		CH3	CH2	_	CHO		()	Calibration Pair		
		0	0	0	0	AIN1(+) - AIN1		0		
		0	0	0	1	AIN2(+) – AIN2		1		
		0	0	1	0	AIN3(+) – AIN3		2		
	1	0	0	1	1	AIN4(+) – AIN4	(-)	3		

Bit Location	Bit Name	Descrip	otion				
		0	1	0	0	AIN5(+) – AIN5(-)	3
		0	1	0	1	AIN6(+) – AIN6(-)	3
		0	1	1	0	Temp Sensor	Automatically selects the internal reference and sets the gain to 1
		0	1	1	1	VDD Monitor	Automatically selects the internal 1.17 V reference and sets the gain to 1/6
		1	0	0	0	AIN1(-) – AIN1(-)	0
		1	0	0	1	Reserved	
		1	0	1	0	Reserved	
		1	0	1	1	Reserved	
		1	1	0	0	Reserved	
		1	1	0	1	Reserved	
		1	1	1	0	Reserved	
		1	1	1	1	Reserved	

DATA REGISTER (RS2, RS1, RS0 = 0, 1, 1; POWER-ON/RESET = 0x000000)

The conversion result from the ADC is stored in this data register. This is a read-only register. On completion of a read operation from this register, the $\overline{\text{RDY}}$ bit/pin is set.

ID REGISTER (RS2, RS1, RS0 = 1, 0, 0; POWER-ON/RESET = 0xXF)

The Identification Number for the AD7794 is stored in the ID register. This is a read-only register.

IO REGISTER (RS2, RS1, RS0 = 1, 0, 1; POWER-ON/RESET = 0x00)

The I/O register is an 8-bit register from which data can be read or to which data can be written. This register is used to enable the excitation currents and select the value of the excitation currents. Table 12 outlines the bit designations for the IO register. IO0 through IO7 indicate the bit locations, IO denoting the bits are in the IO register. IO7 denotes the first bit of the data stream. The number in brackets indicates the power-on/reset default status of that bit.

107	106	105	104	IO3	102	IO1	100
0(0)	IOEN(0)	IO2DAT(0)	IO1DAT(0)	IEXCDIR1(0)	IEXCDIR0(0)	IEXCEN1(0)	IEXCEN0(0)

Table 12 Filter Register Bit Designations

Bit Location	Bit Name	Description							
IO7	0	This bit must be programmed with a Logic 0 for correct operation.							
106	IOEN	Configures th	ne pins AIN6(+)/P2 and AIN6(-)/P2 are analog input pins or digital output pins.					
		When this bit	t is <i>set</i> , the pin:	are configured as digital output pins P1 and P2.					
		When this bit	t is <i>cleared</i> , the	se pins are configured as analog input pins AIN6(+) and AIN6(-).					
105-104	IO2DAT/IO1DAT	P2/P1 Data.							
		When IOEN is	s set, the data	for the digital output pins P1 and P2 is written to bits IO2DAT and IO1DAT.					
103-102	IEXCDIR1-	Direction of Current Sources Select bits.							
	IEXCDIR0	IEXCDIR1	IEXCDIR0	Current Source Direction					
		0	0	Current Source IEXC1 connected to pin IOUT1, Current Source IEXC2 connected to pin IOUT2					
		0	1	Current Source IEXC1 connected to pin IOUT2, Current Source IEXC2 connected to pin IOUT1					
		1 0 Both Current Sources connected to pin IOUT1. Permitted only when the current sources are set to 10 uA or 200 uA							
		1 Both Current Sources connected to pin IOUT2. Permitted only when current sources are set to 10 uA or 200 uA							
IO3-IO2	IEXCEN1-	These bits are	e used to enab	le and disable the current sources along with selecting the value of the					

Bit Location	Bit Name	Description excitation currents.					
	IEXCEN0						
		IEXCEN1	IEXCEN0	Current Source Value			
		0	0	Excitation Currents Disabled			
		0	1	10 uA			
		1	0	200 uA			
		1	1	1 mA			

OFFSET REGISTER (RS2, RS1, RS0 = 1, 1, 0; POWER-ON/RESET = 0x800000)

The offset register holds the offset calibration coefficient for the ADC. The power-on-reset value of the internal zero-scale calibration coefficient register is 800000 hex. The AD7794 has 4 offset registers. Channels AIN1 to AIN3 have dedicated offset registers while channels AIN4, AIN5 and AIN6 share an offset register. Each of these registers is a 24-bit read/write register. This register is used in conjunction with its associated full-scale register to form a register pair. The power-on-reset value is automatically overwritten if an internal or system zero-scale calibration is initiated by the user. The AD7794 must be placed in power down mode or idle mode when writing to the offset register.

FULL-SCALE REGISTER (RS2, RS1, RS0 = 1, 1, 1; POWER-ON/RESET = 0x5XXXX5)

The full-scale registers is a 24-bit register that holds the full-scale calibration coefficient for the ADC. The AD77794 has 4 full-scale registers. Channels AIN1, AIN2 and AIN3 have dedicated full-scale registers while channels AIN4, AIN5 and AIN6 share a register. The full-scale registers are read/write registers. However, when writing to the full-scale registers, the ADC must be placed in power down mode or idle mode. These registers are configured on power-on with factory-calibrated internal full-scale calibration coefficients, the factory calibration being performed with the gain set to 1 and using the internal reference. Therefore, every device will have different default coefficients. These default values are used when the device is operated with a gain of 1 and when the internal reference is selected. For other gains or when the external reference is used at a gain of 1, these default coefficients will be automatically overwritten if an internal or system full-scale calibration is initiated by the user. A full-scale calibration should be performed when the gain is changed.

TYPICAL APPLICATION (FLOWMETER)

